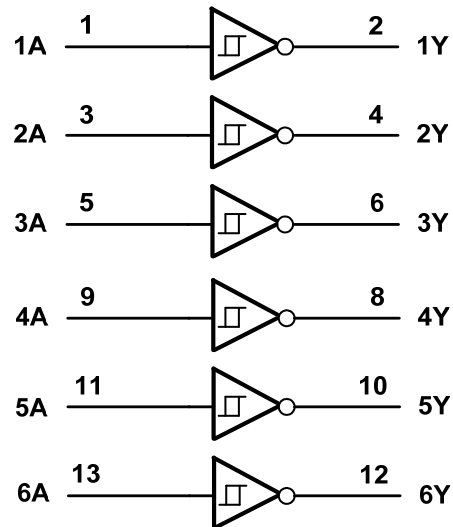


Pin Descriptions

Pin Number	Pin Name	Description
1	1A	Data Input
2	1Y	Data Output
3	2A	Data Input
4	2Y	Data Output
5	3A	Data Input
6	3Y	Data Output
7	GND	Ground
8	4Y	Data Output
9	4A	Data Input
10	5Y	Data Output
11	5A	Data Input
12	6Y	Data Output
13	6A	Data Input
14	VCC	Supply Voltage

Logic Diagram



Function Table

Input	Output
A	Y
H	L
L	H

Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to +7.0	V
V _I	Input Voltage Range note 4	-0.5 to +7.0	V
I _{IK}	Input Clamp Current V _I < 0V	-20	mA
I _{OK}	Output Clamp Current V _O < -0V	-50	mA
I _O	Continuous Output Current - 0.5V < V _O < V _{CC} + 0.5V	±25	mA
I _{CC}	Continuous Current Through V _{CC}	50	mA
I _{GND}	Continuous Current Through GND	-50	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 5) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage	—	2.0	5.5	V
V _I	Input Voltage	—	0	5.5	V
V _O	Output Voltage	—	0	V _{CC}	V
I _{OH}	High-Level Output Current	2.0V	—	-50	mA
		2.3V to 2.7V	—	-2	μA
		3.0V to 3.6V	—	-6	mA
		4.5V to 5.5V	—	-12	mA
I _{OL}	Low-Level Output Current	2.0V	—	50	μA
		2.3V to 2.7V	—	2	mA
		3.0V to 3.6V	—	6	mA
		4.5V to 5.5V	—	12	mA
T _A	Operating Free-Air Temperature	—	-40	+125	°C

Note: 5. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V _{CC}	T _A = -40°C to +85°C		T _A = -40°C to +125°C		Unit
				Min	Max	Min	Max	
V _{T+}	Positive Going Threshold	—	2.5 V	1	1.75	1	1.75	V
		—	3.3 V	1.31	2.31	1.31	2.31	
		—	5.0 V	1.95	3.5	1.95	3.5	
V _{T-}	Negative Going Threshold	—	2.5 V	0.75	1.5	0.75	1.5	—
		—	3.3 V	0.99	2.07	0.99	2.07	
		—	5.0 V	1.5	3.05	1.5	3.05	
V _H	Hysteresis (V _{T+} - V _{T-})	—	2.5 V	0.25	1	0.25	1	V
		—	3.3 V	0.33	1.32	0.33	1.32	
		—	5.0 V	0.5	2	0.5	2	
V _{OH}	High-Level Output Voltage	I _{OH} = -50μA	2.0V to 5.5V	V _{CC} -0.1	—	V _{CC} -0.1	—	V
		I _{OH} = -2mA	2.3V	2.0	—	2.0	—	
		I _{OH} = -6mA	3.0V	2.48	—	2.48	—	
		I _{OH} = -12mA	4.5V	3.8	—	3.8	—	
V _{OL}	Low-Level Output Voltage	I _{OL} = 50μA	2.0V to 5.5V	—	0.1	—	0.1	V
		I _{OL} = 2mA	2.3V	—	0.4	—	0.4	
		I _{OL} = 6mA	3.0V	—	0.44	—	0.44	
		I _{OL} = 12mA	4.5V	—	0.55	—	0.55	
I _{OFF}	Power Down Leakage Current	V _I or V _O = 0 to 5.5V	0V	—	5	—	5	μA
I _I	Input Current	V _I = GND or 5.5V	0 to 5.5V	—	±1	—	±1	μA
I _{CC}	Supply Current	V _I = GND or V _{CC} I _O =0	5.5V	—	20	—	20	μA

Switching Characteristics

Symbol	Parameter	Test Conditions	V _{CC}	T _A = +25°C			-40°C to +85°C		-40°C to +125°C		Unit
				Min	Typ.	Max	Min	Max	Min	Max	
t _{PD}	Propagation Delay A _N to Y _N	Figure 1 C _L = 15pF	2.5V ± 0.2V	—	10.2	19.7	1	22	1	22	ns
			3.3V ± 0.3V	—	7.3	12.8	1	15	1	15.9	
			5.0V ± 0.5V	—	5.1	8.6	1	10	1	10	
		Figure 1 C _L = 50pF	2.5V ± 0.2V	—	13.3	24	1	27	1	27	ns
			3.3V ± 0.3V	—	9.6	16.3	1	18.5	1	19.4	
			5.0V ± 0.5V	—	6.7	10.6	1	12	1	12	

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

Parameter		Test Conditions	V _{CC}	Typ	Unit
C _{pd}	Power Dissipation Capacitance per Gate	F = 10 MHz C _L = 50pF	3.3V	8.8	pF
			5.0V	9.6	

Noise Characteristics

 V_{CC} = 3V, C_L = 50pF T_A = +25°C

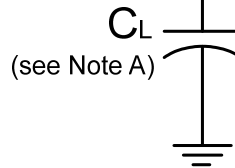
Symbol	Parameter	Min	Typ	Max	Unit
V _{OL(p)}	Quiet output, maximum dynamic V _{OL}	—	0.2	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}	—	-0.1	-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}	—	3.1	—	V
V _{IH(D)}	High Level dynamic input voltage	2.31	—	—	V
V _{IL(D)}	Low Level dynamic input voltage	—	—	0.99	V

Package Characteristics

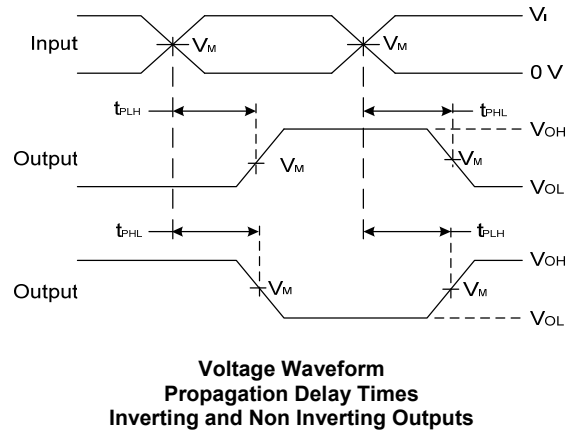
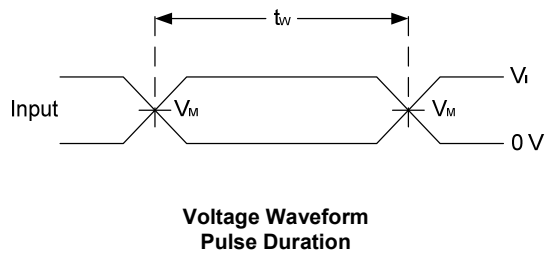
Symbol	Parameter	Test Conditions	V _{CC}	Min	Typ	Max	Unit
C _i	Input Capacitance	V _i = V _{CC} – or GND	2.0 to 5.5V	—	3.3	10	pF

Parameter Measurement Information

From Output
Under Test



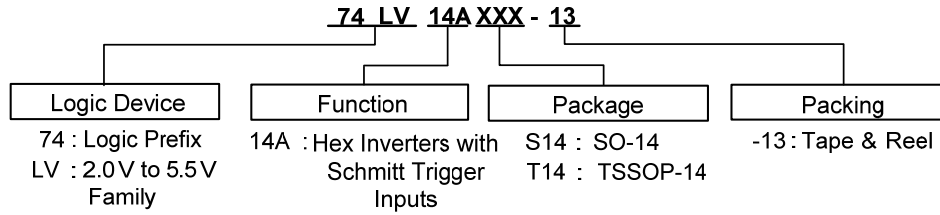
V_{CC}	Inputs		V_M	C_L
	V_I	t_r / t_f		
2.0V to 5.5V	V_{CC}	< 3ns	$V_{CC} / 2$	15pF or 50pF



- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate $\leq 10\text{MHz}$.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{PD} .

Figure 1 Load Circuit and Voltage Waveforms

Ordering Information

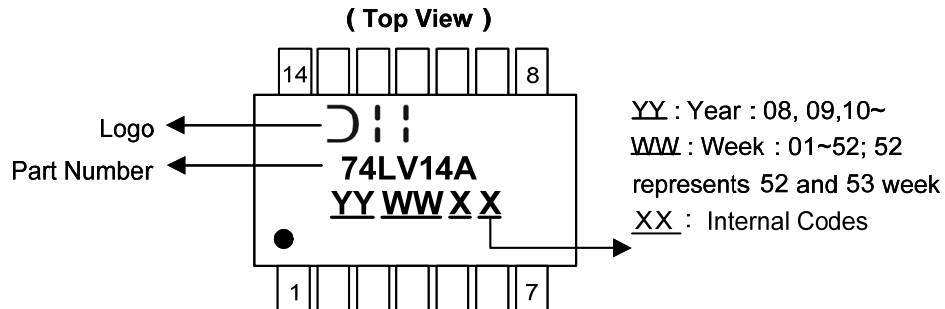


Part Number	Package Code	Packaging (Note 6)	13" Tape and Reel	
			Quantity	Part Number Suffix
74LV14AS14-13	S14	SO-14	2500/Tape & Reel	-13
74LV14AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Note: 6. The taping orientation and tape details can be found at <http://www.diodes.com/datasheets/ap02007.pdf>

Marking Information

(1) SO14, TSSOP14

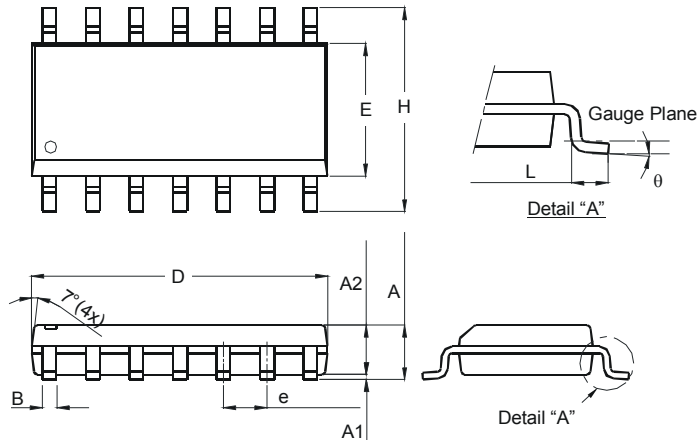


Part Number	Package
74LV14AS14	SO-14
74LV14AT14	TSSOP-14

Package Outline Dimensions (All dimensions in mm.)

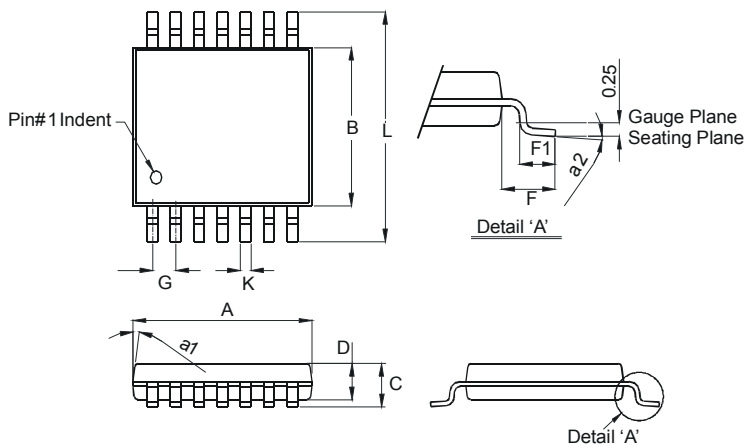
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

Package Type: SO-14



SO-14		
Dim	Min	Max
A	1.47	1.73
A1	0.10	0.25
A2	1.45 Typ	
B	0.33	0.51
D	8.53	8.74
E	3.80	3.99
e	1.27 Typ	
H	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Dimensions in mm		

Package Type: TSSOP-14

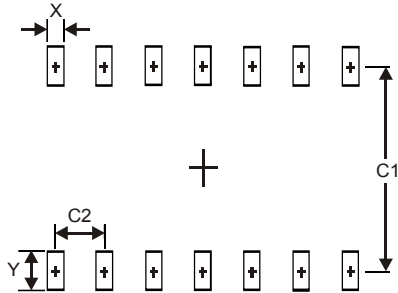


TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
A	4.9	5.10
B	4.30	4.50
C	—	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

Suggested Pad Layout

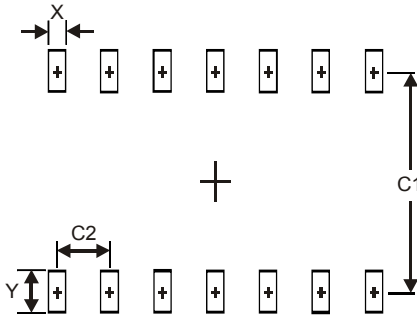
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

Package Type: SO-14



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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